PCN Number:	20210709000.1	**PCN Date:**	July 12, 2021
Title:	Qualification of new Mold compound for select Package Devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	Oct 12, 2021	**Estimated Sample Availability:**	Date Provided at Sample request

Change Type:

☐	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☒	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☐	Test Site	☐	Wafer Fab Site
☐	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

Texas Instruments Incorporated is announcing the qualification of new mold compound for devices listed in the “Product Affected” Section.

Material Difference:

	Current	Proposed
Mold compound	101325958	101374189

Reason for Change:

Continuity of supply.

Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

☒	No Impact to the Material Declaration	☐	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website. There is no impact to the material meeting current regulatory compliance requirements with this PCN change.

Changes to product identification resulting from this PCN:

None

Product Affected:

LM3401MM/NOPB	LM3401MMX/NOPB	LM4990MH/NOPB

Qualification Report

Approve Date 09-Jun-2021

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: LM3401MM/NOPB	Qual Device: LM4990MH/NOPB
PC	Preconditioning	Level 1 - 260C	3/462/0	3/462/0
UHST	Unbiased HAST, 130C	96 Hours	3/231/0	3/231/0
TC	Temperature Cycle, -65C/150C	500 Cycles	3/231/0	-
MSL	Moisture Sensitivity	Level 1 - 260C	3/36/0	3/36/0
SD	Solderability with Bake Precon	Pb-Free	3/Pass	-
LFA	Lead Finish Adhesion	Leads	3/45/0	-
MQ	Manufacturability (Assembly)	(per mfg. site requirements)	3/Pass	3/Pass
DS	Die Shear	Die	3/30/0	3/30/0
WBP	Bond Pull	Wires	3/228/0	3/228/0
XRAY	X-Ray	Top side only	3/15/0	3/15/0
YLD	FTY and Bin Summary	-	3/Pass	3/Pass

- Qual Device LM4990MH/NOPB is qualified at LEVEL3-260C
- Qual Device LM3401MM/NOPB is qualified at LEVEL1-260C

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1000 Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent Temperature Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/
Green/Pb-free Status:
Qualified Pb-Free(SMT) and Green

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